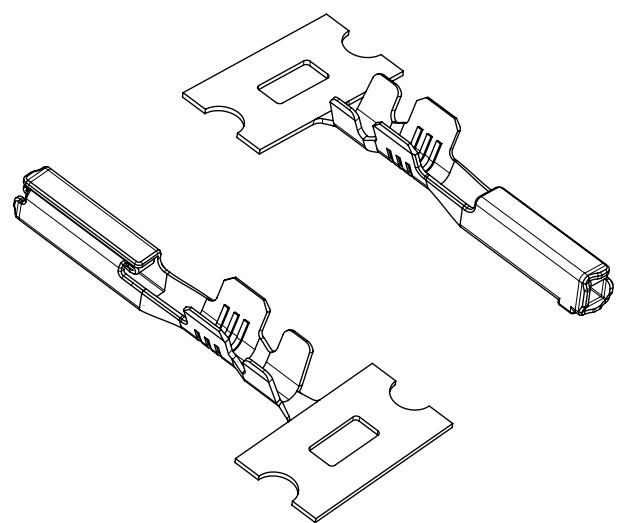
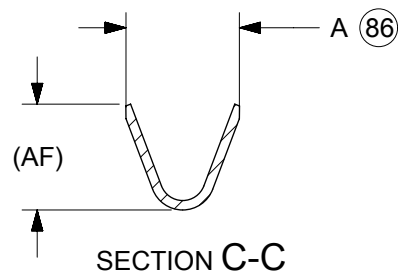
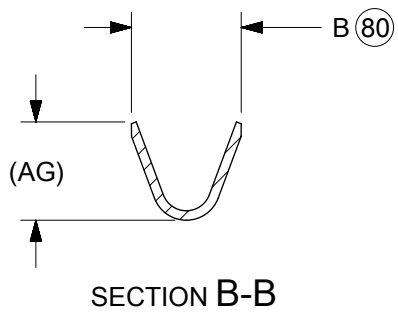
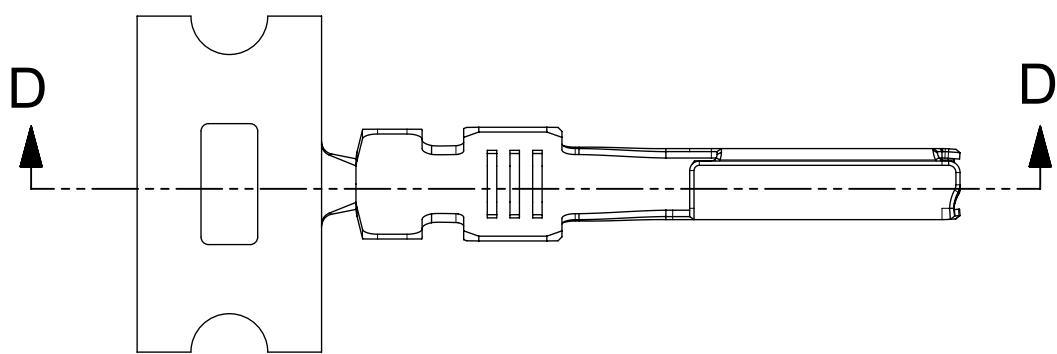
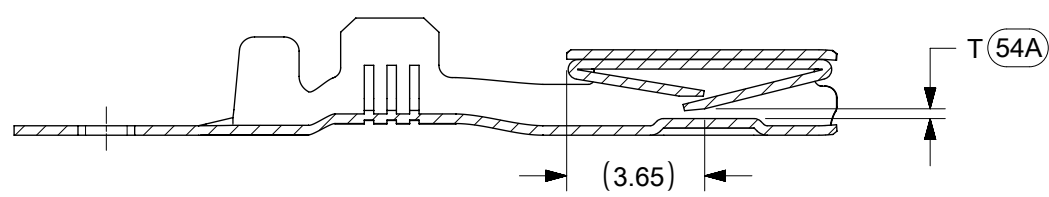
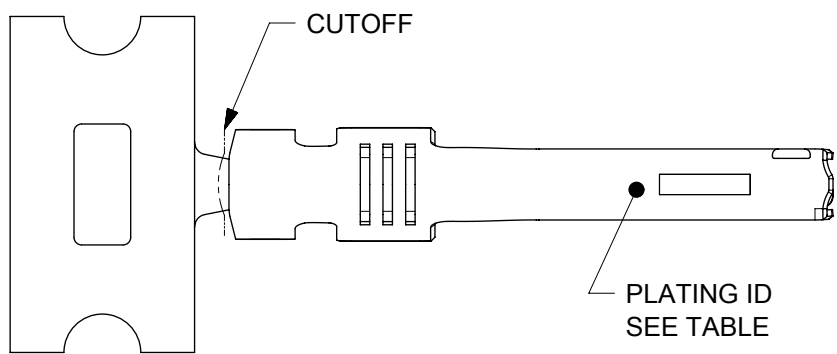
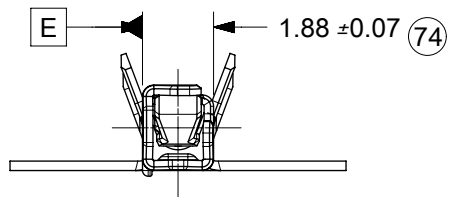
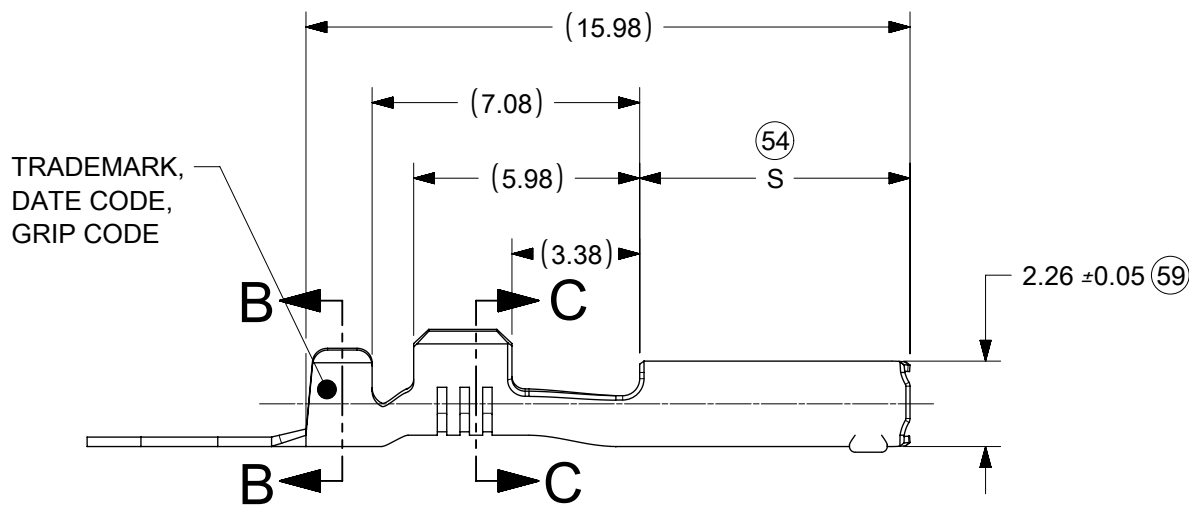
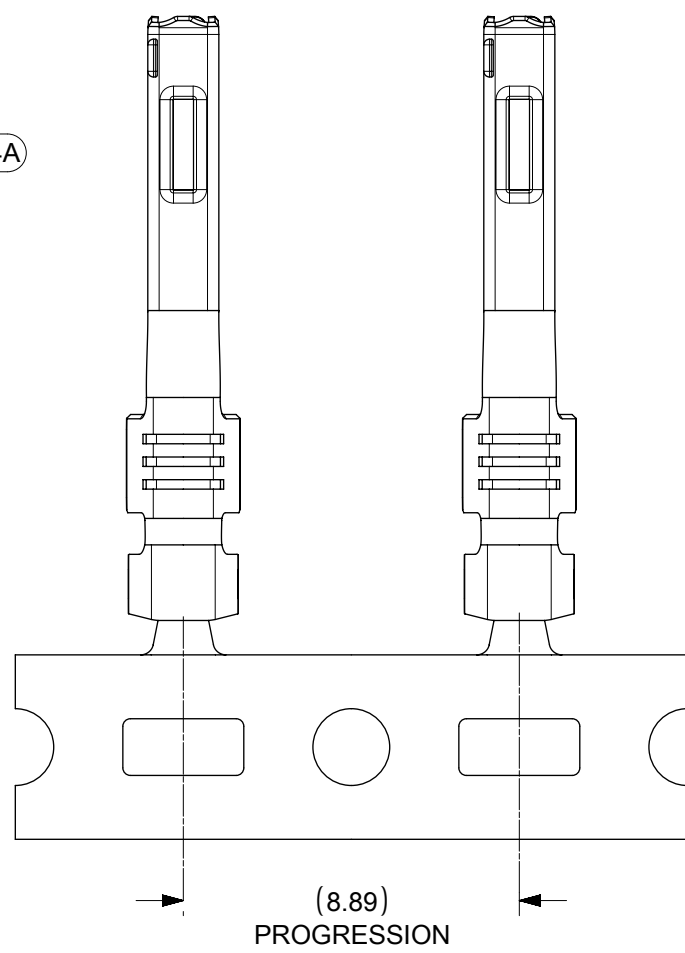




ISO VIEWS
SCALE 3:1



SECTION D-D



- NOTES: (UNLESS OTHERWISE SPECIFIED)
- MATERIALS: SEE TABLE
 - PACKAGING SPECIFICATION: PK-31300-516 AND PK-30907-759
 - CRIMPING PER APPLICATION SPECIFICATION AS-33468-001
 - CRIMPED LEAD MEETS THE FOLLOWING:
 - SAE/USCAR-21, MAY 2002
 - SAE/USCAR-2, REV. 3, APRIL 2001
 - SAE/USCAR-12, REV. 2
 - GMW #3191 AUGUST 22, 2000 (DRAFT) TEMPERATURE CLASS 3, APPLIES ONLY TO Au PARTS
 - GMW #3191 JANUARY, 2005 TEMPERATURE CLASS 3, APPLIES ONLY TO Ag PARTS
 - PLATING NOTES:
 - TIN PLATING (ENTIRE TERMINAL)
 - ELECTRO REFLOW 1.90 - 3.30 MICROMETERS TIN OVER 0.25 - 0.76 MICROMETERS NICKEL
 - GOLD PLATING
 - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - ELECTRODEPOSITED GOLD 0.76 - 1.5 MICROMETERS IN CONTACT AREAS
 - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA
 - SILVER PLATING
 - UNDERPLATE OVERALL 1.25-2.25 MICROMETERS DUCTILE SULPHAMATE NICKEL
 - ELECTRODEPOSITED PURE SILVER 99.5% PURITY SEMI-BRIGHT FINISH WITH NO BRIGHTENERS OR CHROMATES 1.9 - 3.3 MICROMETERS IN CONTACT AREAS
 - ANTI-TARNISH TREATMENT FOR SILVER PLATED AREA: SYNTHETIC HYDROCARBON CONTACT SURFACE FINISH OR EQUIVALENT
 - ELECTRODEPOSITED TIN MATTE FINISH 2.5 - 4.0 MICROMETERS IN CRIMP AREA

WIRE SIZE	GRIP CODE	PART NUMBER	REEL PAYOFF DIRECTION	DIM A	DIM B	DIM S	DIM T	DIM AF	DIM AG	BASE MATERIAL	PLATING ID
22 AWG	A	33468-0002	D	2.3	2.3	7.15	0.26	(2.1)	(2.1)	COPPER ALLOY	Sn Lead Free
		33468-0001	B			±0.10	±0.07				
		33467-0004	D	2.3	2.3	6.97-	0.26	(2.1)	(2.1)	COPPER ALLOY	Au Lead Free
		33467-0003	B			7.27	±0.07				
		34736-1001	D	2.3	2.3	6.97-	0.26	(2.1)	(2.1)	COPPER ALLOY	Ag Lead Free
		34736-2001	B			7.27	±0.07				
18/20 AWG	B	33468-0004	D	3.0	2.9	7.15	0.26	(2.8)	(2.6)	COPPER ALLOY	Sn Lead Free
		33468-0003	B			±0.10	±0.07				
		33467-0006	D	3.0	2.9	6.97-	0.26	(2.8)	(2.6)	COPPER ALLOY	Au Lead Free
		33467-0005	B			7.27	±0.07				
		34736-1002	D	3.0	2.9	6.97-	0.26	(2.8)	(2.6)	COPPER ALLOY	Ag Lead Free
		34736-2002	B			7.27	±0.07				

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DIMENSION UNITS	SCALE	CURRENT REV DESC:
mm	5:1	
GENERAL TOLERANCES (UNLESS SPECIFIED)		
ANGULAR TOL	± 3	
4 PLACES	±	
3 PLACES	±	
2 PLACES	± 0.10	
1 PLACE	± 0.3	
0 PLACES	±	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

EC NO: 601885		2018/05/31 2018/08/09 2018/08/13
DRWN: NVENKATESHSH		
CHK'D: JPRUNEAU		
APPR: TOMSMITH		
INITIAL REVISION:		2007/04/12 2007/04/13
DRWN: DHEMNANI		
APPR: BMOSER		
THIRD ANGLE PROJECTION	DRAWING	SERIES
	C-SIZE	33468

mo

lex

MX64 SAE
RECEPTACLE TERMINAL

PRODUCT CUSTOMER DRAWING

DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
SD-33468-001	PSD	001	G3
MATERIAL NUMBER	CUSTOMER		SHEET NUMBER
SEE TABLE	GENERAL MARKET		1 OF 1

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Molex:

[33467-0004 \(Loose Piece\)](#) [33467-0005 \(Loose Piece\)](#) [33467-0006 \(Loose Piece\)](#)